



DXM Wafer Mounter

The DXM Wafer Mounter is used for mounting wafers prior to the singulation/dicing process. This prevents die edge chipping during shipping or the pick and place operation.

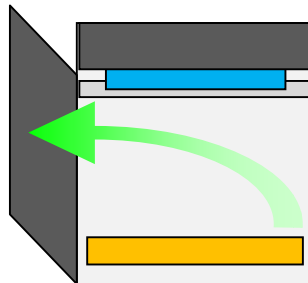
Applications

- Scribe & Break
- Laser-dicing
- Saw-dicing

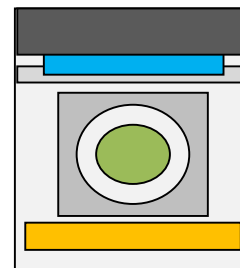


• DXM Wafer Mounter has been designed to provide the capability of mounting tape to saw frames and to expand the space between diced semiconductor die by omnidirectional stretching of the plastic film on which these die have been mounted. The stretching is done over concentric hoop sets that retain the stretched plastic films.

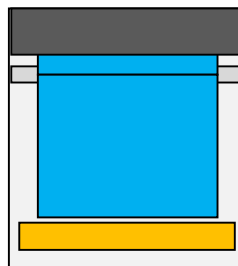
Sequence of Operation:



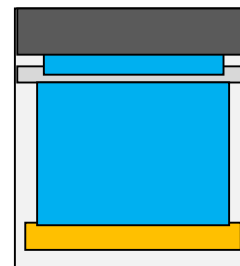
1. Open Cover. Cover opens to the left to allow easy access in operation



2. Place wafer and film frame face down. Align film frame to alignment pins. (not shown). Mount wafer concentrically to film frame.



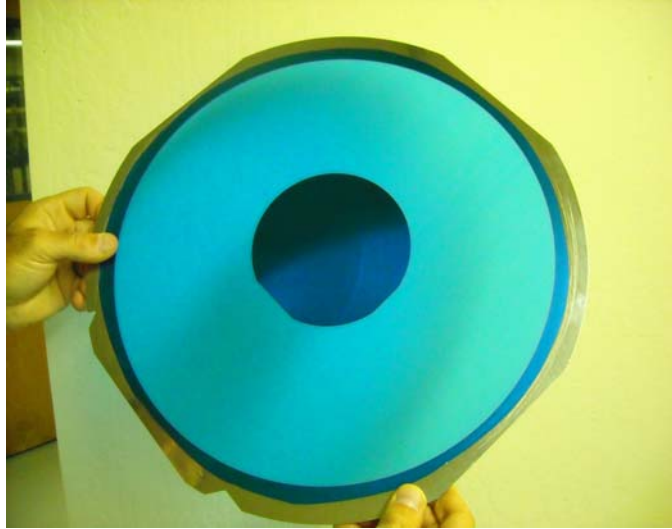
3. Draw wafer mount tape from roll over wafer and film frame.



4. Squeegee tape onto wafer and film frame, cut tape and remove.

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The Final Product:



After four quick and easy operation steps your wafer is now mounted and ready for down stream processing. The tension and adhesion of the tape is designed to endure the many physical challenges associated with saw-dicing, backgrinding, scribing, breaking, and pick and place operations.

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DXM Wafer Mounter Specifications

- Film Frames accommodated
 - FF-105 (or similar) accommodates 8 inch (200mm) wafers and smaller
 - FF-108 (or similar) accommodates 8 inch (200mm) wafers and smaller
 - FF-123 (or similar) accommodates 12 inch (300mm) wafers and smaller
 - Other film frame configurations available on request
 - XX denotes operating voltage: 01 for 100/120 VAC, 02 for 220/240 VAC
 - Hoops available on request
 - Custom configuration available on request
- Power Required: 100/120 VAC 5 amp OR 220/240 VAC 3 amp, 50/60Hz
- Operating Temperature: Ambient to 225° F (107° C)
- Dimensions
 - Height 10 in (254 mm)
 - Width 20 in (508 mm)
 - Depth 30 in (762 mm)
- Can accommodate tape up to 17" wide.



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